

Title (en)

Process for manufacturing an adhesion promoting layer

Title (de)

Verfahren zur Herstellung von Haftvermittlerschichten

Title (fr)

Procédure pour la fabrication d'une couche promotrice d'adhésion

Publication

EP 0949013 A3 20030416 (DE)

Application

EP 99106117 A 19990401

Priority

DE 19815182 A 19980404

Abstract (en)

[origin: EP0949013A2] Coupling agent layers are applied onto a strip material (1) by low pressure plasma polymerisation as the strip moves continuously through a plasma zone (3), the plasma being produced by electrical discharge, preferably a kHz, MHz or GHz discharge. An Independent claim is also included for a use of the coupling agent between the carrier strip (1) and adhesive on a single or double sided adhesive strip. Preferred features: A coupling agent coating is applied under a gas pressure of 10<-3> to 20 mbar and the electrical discharges are pulsed. The strip material moves at NOTLESS 0.1 m/min, preferably NOTLESS 50 m/min giving coating times NOTGREATER 1 minute, preferably NOTGREATER 1 second. The unwinding station (2), winding up station (9) and plasma zone (3) are housed in a vacuum chamber or the strip material can be guided through vacuum sluices into the plasma zone. The coupling agent is almost or completely transparent.

IPC 1-7

B05D 7/24; B05D 5/10

IPC 8 full level

B05D 5/10 (2006.01); **B05D 7/24** (2006.01)

CPC (source: EP US)

B05D 1/62 (2013.01 - EP US)

Citation (search report)

- [XY] DE 3521625 A1 19861218 - LEYBOLD HERAEUS GMBH & CO KG [DE]
- [Y] US 5718967 A 19980217 - HU ING-FENG [US], et al
- [Y] US 3814983 A 19740604 - WEISSFLOCH C, et al
- [A] US 4563388 A 19860107 - BONK THOMAS J [US], et al

Cited by

EP1129791A3; US6027777A; EP1212785A4

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DOCDB simple family (publication)

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DOCDB simple family (application)

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